

119TH CONGRESS
1ST SESSION

H. R. 6207

To prohibit purchases of certain semiconductor manufacturing equipment from foreign entities of concern or subsidiaries of foreign entities of concern, and for other purposes.

IN THE HOUSE OF REPRESENTATIVES

NOVEMBER 20, 2025

Ms. LOFGREN (for herself, Mr. OBERNOLTE, Mr. KRISHNAMOORTHY, Mr. MOOLENAAR, Mr. LANDSMAN, and Mrs. HOUGHIN) introduced the following bill; which was referred to the Committee on Energy and Commerce, and in addition to the Committee on Science, Space, and Technology, for a period to be subsequently determined by the Speaker, in each case for consideration of such provisions as fall within the jurisdiction of the committee concerned

A BILL

To prohibit purchases of certain semiconductor manufacturing equipment from foreign entities of concern or subsidiaries of foreign entities of concern, and for other purposes.

1 *Be it enacted by the Senate and House of Representa-*
2 *tives of the United States of America in Congress assembled,*

3 **SECTION 1. SHORT TITLE.**

4 This Act may be cited as the “Chip Equipment Qual-
5 ity, Usefulness, and Integrity Protection Act of 2025” or
6 the “Chip EQUIP Act”.

1 **SEC. 2. PURCHASES OF SEMICONDUCTOR MANUFAC-**
2 **TURING EQUIPMENT.**

3 (a) DEFINITIONS.—Section 9901 of the William M.
4 (Mac) Thornberry National Defense Authorization Act for
5 Fiscal Year 2021 (15 U.S.C. 4651) is amended by adding
6 at the end the following:

7 “(14) The term ‘completed, fully assembled’,
8 with respect to semiconductor manufacturing equip-
9 ment, means the state in which all (or substantially
10 all) necessary parts, chambers, subsystems, and sub-
11 components have been put together, resulting in
12 such equipment that is—

13 “(A) ready-to-use or ready-to-install; and

14 “(B) ready to be purchased directly from
15 an entity.

16 “(15) The term ‘ineligible semiconductor manu-
17 facturing equipment’—

18 “(A) means completed, fully assembled
19 equipment that is manufactured, assembled, or
20 refurbished by a foreign entity of concern or
21 subsidiary thereof and designed for use in the
22 fabrication, assembly, testing, advanced pack-
23 aging, production, or research and development
24 of semiconductors;

25 “(B) includes—

26 “(i) deposition equipment;

1 “(ii) etching equipment;
 2 “(iii) lithography equipment;
 3 “(iv) inspection, measuring, and test
 4 equipment;
 5 “(v) wafer slicing equipment;
 6 “(vi) wafer dicing equipment;
 7 “(vii) wire bonders;
 8 “(viii) ion implantation equipment;
 9 “(ix) chemical mechanical polishing;
 10 “(x) diffusion or oxidation furnaces;
 11 “(xi) thermal processing equipment;
 12 and
 13 “(xii) automated material handling
 14 systems; and
 15 “(C) does not include any part, chamber,
 16 subsystem, or subcomponent that enables or is
 17 incorporated into such equipment.”.

18 (b) INELIGIBLE USE OF FUNDS.—Section 9909 of
 19 the William M. (Mac) Thornberry National Defense Au-
 20 thorization Act for Fiscal Year 2021 (15 U.S.C. 4659)
 21 is amended—

22 (1) by redesignating subsection (f) as sub-
 23 section (g); and
 24 (2) by inserting after subsection (e) the fol-
 25 lowing new subsection:

1 “(f) INELIGIBLE USE OF FUNDS.—

2 “(1) IN GENERAL.—Subject to paragraph (2),
3 the Secretary shall include in the terms of each
4 agreement with a covered entity for the award of
5 Federal financial assistance under section 9902, or
6 with the recipient of an award made under section
7 9906, prohibitions with respect to a project relating
8 to the procurement, installation, or use of ineligible
9 semiconductor manufacturing equipment, to be ef-
10 fective for 10 years beginning on the date on which
11 the agreement is signed.

12 “(2) WAIVER.—The Secretary may waive the
13 prohibitions referred to in paragraph (1) if—

14 “(A) the ineligible semiconductor manufac-
15 turing equipment to be purchased by the appli-
16 cable covered entity is not produced in the
17 United States or an allied or partner country in
18 sufficient and reasonably available quantities or
19 of a satisfactory quality to support established
20 or expected production capabilities;

21 “(B) the ineligible semiconductor manufac-
22 turing equipment at issue was manufactured or
23 assembled by an entity that is not a foreign en-
24 tity of concern or subsidiary thereof and was

1 refurbished by a foreign entity of concern or
2 subsidiary thereof; or

3 “(C)(i) the use of the ineligible semicon-
4 ductor manufacturing equipment complies with
5 the requirements set forth in the Export Ad-
6 ministration Regulations (as such term is de-
7 fined in section 1742 of the Export Control Re-
8 form Act of 2018 (50 U.S.C. 4801)); and

9 “(ii) the Secretary, in consultation
10 with the Director of National Intelligence
11 or the Secretary of Defense, determines
12 such waiver is in the national security in-
13 terest of the United States.

14 “(3) FOREIGN ENTITIES OF CONCERN.—Noth-
15 ing in this subsection may be construed to waive the
16 application of section 9907.”.

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